PROCESS CP283

Power Transistor

NPN - Silicon Power Transistor Chip

Central™
Semiconductor Corp.

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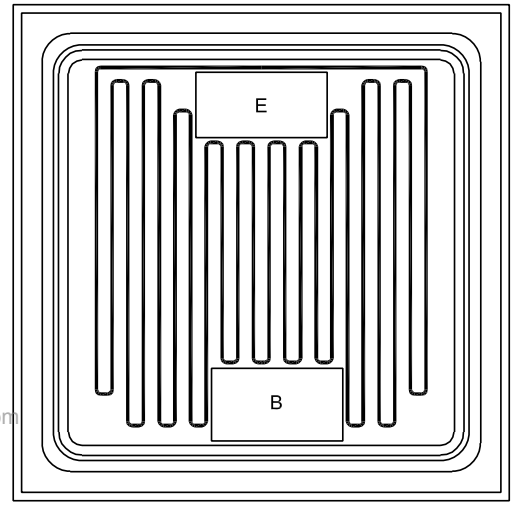
PROCESS DETAILS

Die Size	68 x 68 MILS
Die Thickness	9.5 MILS
Base Bonding Pad Area	18 x 11 MILS
Emitter Bonding Pad Area	18 x 12 MILS
Top Side Metalization	Al - 45,000Å
Back Side Metalization	Ti/Ni/Ag - (3000Å, 10,000Å, 10,000Å)

GEOMETRY



BACKSIDE COLLECTOR R0

GROSS DIE PER 5 INCH WAFER
3,675

PRINCIPAL DEVICE TYPES
MJE13003

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